

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the above-captioned patent application:

**Listing of Claims:**

1. (Currently Amended) A package for retaining and dispensing at least one semiconductor crystal for use in a ~~vacuum-deposition~~ processing apparatus, said package comprising:

a plurality of semiconductor crystals, each of said crystals being defined by a planar disk structure having peripheral edges and further including a center active region on at least one side thereof;

a tray portion having a plurality of vertically disposed supporting slots for retaining a said ~~crystal~~ plurality of crystals, each of said vertically disposed supporting slots being configured to support only the peripheral edges of each said crystal retained therein; and

a cover portion rotatably mounted in overlaying fashion relative to said tray portion, said cover portion including a slotted opening permitting alignment with at least one said vertically disposed supporting slot of said tray portion.

2. (Original) A package according to Claim 1, wherein said tray portion is circular.

3. (Canceled).

4. (Currently Amended) A package according to Claim 1, including ~~means for retaining~~ a crystal removal tool, and means for retaining said crystal removal tool.

5. (Original) A package according to Claim 4, wherein said removal tool is releasably attached to said package.

6. (Original) A package according to Claim 2, wherein a plurality of said crystal packages can be stacked for storage.
7. (Original) A package according to Claim 6, wherein a plurality of said packages can be stacked vertically.
8. (Currently Amended) A package according to Claim ~~3~~ 1, wherein each vertically disposed supporting slot includes an inner wall and an outer wall, said inner wall having an ~~inward~~ inwardly radially extending recess, said recess being sized to permit said peripheral edges of a said crystal to contact said inner wall but in which said center active region is aligned with said recess such that said center active region is protected from contact within the package.
9. (Original) A package according to Claim 5, wherein said removal tool includes a vertical slot that can be aligned with a vertically disposed supporting slot.
10. (Currently Amended) A package according to Claim ~~3~~ 8, wherein each vertically disposed supporting slot includes an inner wall and an outer wall, said outer wall including a center scalloped region to permit access to a supported crystal.
11. (Original) A package according to Claim 1, including a detent mechanism for permitting the slotted opening of the cover portion to be indexed to a plurality of radial positions relative to the tray portion.
12. (Original) A package according to Claim 2, wherein each of said supporting slots are substantially equally spaced between each other in a circumferential manner with the exception of a larger spacing between at least two of said slots defining a position for aligning initially with said slotted opening of said cover portion.

13. (Original) A method for plurality of disc-like crystals for use in vacuum deposition processing apparatus, each of said crystals having an active center region on one side thereof, said method including the steps of:

providing a package having a plurality of vertically arranged slots on a tray portion, each of said slots including means for retaining a said crystal without contacting the center region of said crystal, said package further including a cover covering said slots;

rotating said cover about said tray portion until a slotted opening of said cover is aligned with a vertical slot; and

removing a said crystal.

14. (Original) A method as recited in Claim 13, wherein said removing step includes the step of using a pair of tweezers.

15. (Original) A method as recited in Claim 13, wherein said removing step includes the step of removing a said crystal using a removal tool.

16. (Original) A method as recited in Claim 15, wherein said removal tool includes a vertical slot, said removing step further including the step of

aligning said vertical slot with the aligned openings of said package and allowing said crystal to be retained by said tool.

17. (Original) A method as recited in Claim 15, wherein said removal tool is provided on said package.